ASSOCIATION CONNECT: ELECTRONICS INDUSTR	Material Compos © Copyright 2005. IPC international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and M	ials and Mfg Information			
upplier Infor	mation				·										
Company name*			Company unique ID			ī	Unique ID Authority				Response Date*				
nsemi											2024-05-04				
Contact Name		Title - Contact]	Phone - Contact*				Email - Contact*					
Product-Env-Stew	vards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Reques	ster Item Number	Mfr Item Number		Mfr Item Name			Effective Dat	e Versi	on	Manufacturing Site	,	Weight*	UOM	Unit Type	
		NRVS10	SIGFL SR SOD123F GPPN 1A		PN 1A 400V		2024-05-04			TSCBE		15.0	mg	Each	
Ianufacturing	g Proccess Information	on						•							
Terminal Plating / Grid Array Material T		Perminal Base Alloy J-STD-020 MS		SL Rating	Peak Process Body Tempera		y Temperatu	ture Max Time at Peak Tempera		ure Numb	er of Reflow Cyc	eles			
Matte Tin (Sn) - annealed			CU Alloy 1				260 C 30		30	seconds 3					
omments															
vel 1 - maximum	time at peak temperature	e during sol	dering is 10-3	30 seconds											
or more informat	tion regarding material co	omposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	1.52	mg	Supplier	Copper (Cu)	7440-50-8		1.52	mg
Die	0.997	mg	Supplier	Silicon (Si)	7440-21-3		0.8973	mg
			В	Nickel (Ni)	7440-02-0		0.0065	mg
			Supplier	Gold (Au)	7440-57-5		0.0015	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0917	mg
Die Attach Solder	0.408	mg	Supplier	Silver (Ag)	7440-22-4		0.0102	mg
			A	Lead (Pb)	7439-92-1	7a	0.3774	mg
			Supplier	Tin (Sn)	7440-31-5		0.0204	mg
Lead Frame	5.584	mg	Supplier	Iron (Fe)	7439-89-6		0.0056	mg
			Supplier	Copper (Cu)	7440-50-8		5.5767	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0017	mg
Mold Compound-Black	6.292	mg		Epoxy resin	proprietary data		0.3146	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1258	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.1573	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0315	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.6628	mg
Plating	0.199	mg	Supplier	Tin (Sn)	7440-31-5		0.199	mg